

Scott Hatfield

From: Dan Mis [dmis@unitive.com]
Sent: Thursday, August 09, 2001 6:24 PM
To: 'shatfield@carolinapatents.com'
Subject: Re: Methods of Forming Metallurgy Structures For Wire and Solder Bonding And Related Structures

Scott,
We received the docs but I am out of town and will not be back in town until the 20th.

Dan

Sent from my BlackBerry Wireless Handheld (www.BlackBerry.net)